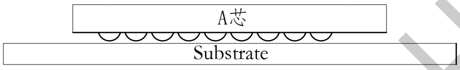
池州华宇电子科技股份有限公司
CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD

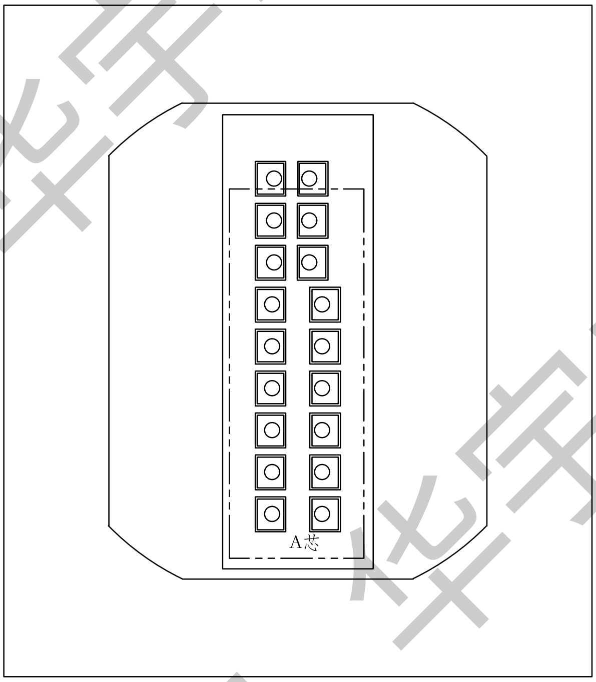
焊线图纸 Bonding Diagram

客户代码 Customer No.		线图号 Drawing No.		页码 Page
产品名称 Product Type		封装外型 PKG Type	LGA24(16.0×14.0×0.75-P1.00)	

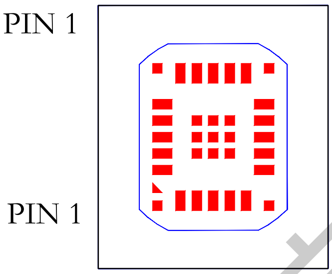
焊线种类 Wire Type	焊线直径(μm) Wire Diameter	焊线根数 NO. of wire	焊线总长(μm) Total wire length	最长线长(μm) Longest wire length	最短线长(μm) Shortest wire length	塑封料型号(绿色环保) Compound Type (Green)	基板编码 Substrate No.
--	--	--	--	--	--	首选(Preferred)：G760L TypeA 备选(Optional)：	

客户图号 Customer drawing NO.	



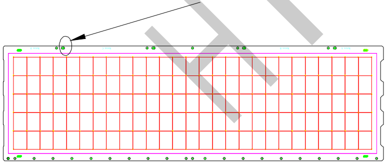


注意：A芯为CSP芯片，锡球向下。



底部示意图

框架传送方向（装片）：
L/F Direction（D/A）：椭圆孔朝上



实物图：
Chip photo：

特殊说明 Special Instructions：

DB注意：
1.装片位置公差为±30um;

NO.	Item	Reference	value	package	KD P/N	Quantity
1	A芯		CSP芯片	10819*3582 (μm²) 425.95*141.02(mil²)	8 inch芯片（非LOW-K） 360 um厚度	1
2	基板	substrate	基板	/		1
3	锡膏	/	F590 SnCu0.7-89M4	/		/
SMT元器件总计						1

拟制 Prepared by		制图日期 Create Date		生效日期 Effective Date		客户确认签字/盖章: Customer Signature
研发审核 R&d check		产品工程审核 Product engineering check		批准 Approved by		

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*warm tips: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as drawing mistakes, which will produce inestimable loss. Thank you